Solution-Processed Copper-Nickel Nanowire Anodes for Organic Solar Cells

Ian E. Stewart,^{a, †} Aaron R. Rathmell,^{a, †} Liang Yan,^b Shengrong Ye,^a Patrick F. Flowers,^a Wei You^{b,c} and Benjamin J. Wilev^{a,*}

^aDepartment of Chemistry, Duke University, 124 Science Drive, Box 90354 Durham, North Carolina 27708, United States. E-mail: benjamin.wiley@duke.edu

^bDepartment of Chemistry, University of North Carolina at Chapel Hill, Chapel Hill, North

Carolina 27599, United States. E-mail: wyou@email.unc.edu

^cCurriculum in Applied Sciences and Engineering, University of North Carolina at Chapel Hill,

Chapel Hill, North Carolina 27599, United States

[†]These authors contributed equally to this work.

Table S-1. Palladium Cost Calculation.

| g Cu/ g Pd ^a | g m ⁻² Cu ^b | g m ⁻² Pd | Bulk \$ Pd g ⁻¹ | \$ Pd m ⁻² |
|-------------------------|-----------------------------------|----------------------|----------------------------|------------------------------|
| 10.2 | 0.0493 | 0.00482 | 26.6 | 0.13 |

^{*a*} Determined by AAS.

^b Mass of Cu per coated slide was determined by Equation S-1

$$m_{\rm Cu} = V_{\rm NW} \times \rho_{\rm Cu} \times \# NW$$
S-1

where m_{Cu} is the mass of copper nanowires, V_{NW} is the average volume of a nanowire determined by the average diameter and length of the nanowire and assuming a cylindrical shape, ρ_{Cu} is the bulk density of copper, and #NW is the number of nanowires m⁻² as determined by Equation S-2

$$\#NW = \frac{AF}{D_{\rm NW} \times L_{\rm NW}}$$
 S-2

where AF is the area covered by the nanowires per m², D_{NW} is the average diameter of the nanowires, and L_{NW} is the average length of the nanowires. Here, the fractional area coverage corresponding to a %*T* of 91.5 with nanowire aspect ratio L/D = 300 is roughly 0.09 m⁻².³⁰



Figure S-1. (A) Plot of transmittance vs. sheet resistance of CuNW films treated with glacial acetic acid and pressed at various pressures. (B) SEM image of a Cu NW film pressed at 160 bar.



Figure S-2. The mole percent of Ni plated onto the Cu NWs versus time in the plating solution.

| Anode | $R_s (\Omega \text{ sq}^{-1})$ | <i>%T</i> of Film and Substrate | %T of Device | % Light Absorbed by Device |
|---------|--------------------------------|---------------------------------|--------------|-------------------------------|
| ITO | 20 | 88 | 10.6 | 77.4 |
| Ag NW | 14 | 67 | 4.3 | 62.7 |
| CuNi NW | 36 | 71 | 6.7 | 64.3 |

Table S-2. Film and Device Characteristics ($\lambda = 550$ nm).